



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Lua et al.

Serial No.: 10/634,123

Filed: August 4, 2003

For: SEMICONDUCTOR SUBSTRATES
INCLUDING I/O REDISTRIBUTION
USING WIRE BONDS AND
ANISOTROPICALLY CONDUCTIVE FILM
AND ASSEMBLIES INCLUDING SAME
(as amended)

Confirmation No.: 5763

Examiner: L. Andujar

Group Art Unit: 2826

Attorney Docket No.: 2269-5709US
(02-1462.00/US)

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March 13, 2006

NOTICE OF EXPRESS MAILING

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Person making Deposit: Timothy Palfreyman

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the title appear on page 3 of this paper;

Amendments to the specification begin on page 4 of this paper;

A listing of the claims begins on page 7 of this paper;

Corrections to the drawings are summarized on page 12 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

Remarks start at page 13 of this paper.

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please amend the title as follows:

**SEMICONDUCTOR SUBSTRATES INCLUDING I/O REDISTRIBUTION
USING WIRE BONDS AND ANISOTROPICALLY CONDUCTIVE ~~FILM~~, FILM
~~METHODS OF FABRICATION~~ AND ASSEMBLIES INCLUDING SAME**